

IN THE CLAIMS

1. (Original) A semiconductor device, comprising:

square first semiconductor chip and square second semiconductor chip laminated with their respective one main surfaces opposite to each other;

a supporting lead a part of which is arranged between one main surface of the first semiconductor chip and one main surface of the second semiconductor chip; and

a resin sealing body that seals the first semiconductor chip, the second semiconductor chip and the supporting lead, wherein:

the respective one main surfaces of the first semiconductor chip and the second semiconductor chip are bonded to a part of the supporting lead via an adhesive layer; and

a part of the supporting lead is formed so that it has smaller width than the respective sides of the first semiconductor chip and the second semiconductor chip.

Claims 2-22 (Canceled)